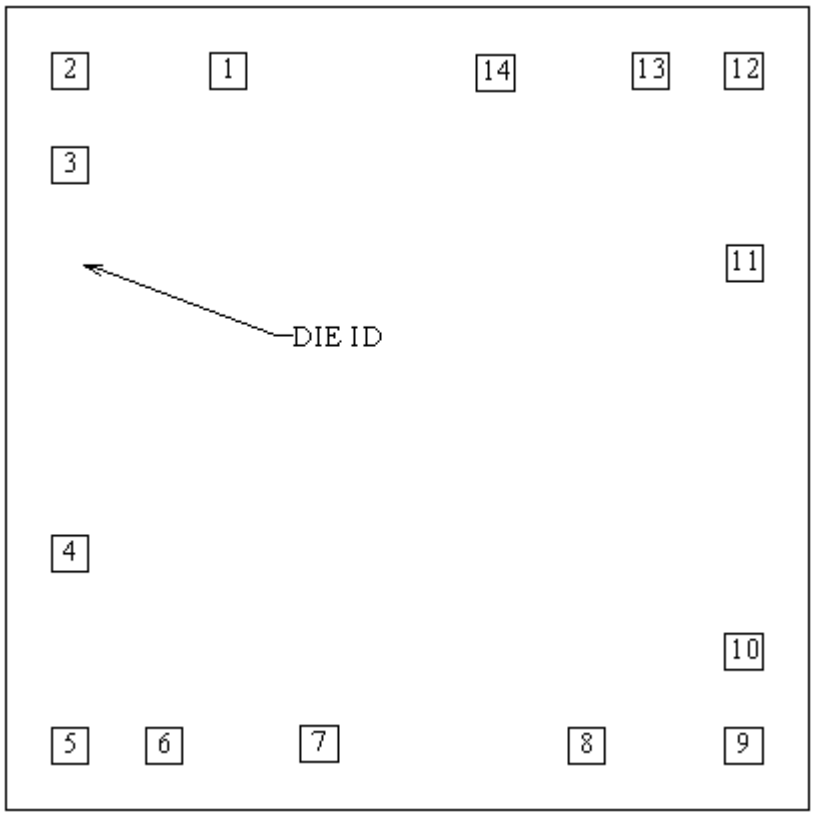
LMC6044 MDC MWC
CMOS QUAD MICROPOWER OPERATIONAL AMPLIFIER

October 29,2015

DIE LAYOUT (B -STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC6044B	Bond Pad Opening Size (min)	88µm x 88µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	200mm	Back Side Metal	Bare Back
Die Size (Drawn)	1905µm x 1905µm 75.0mils x 75.0mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	223µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT 1	1	-426	800	88	x	88
INPUT 1-	2	-801	800	88	x	88
INPUT 1+	3	-801	577	88	x	88
V+	4	-801	-345	88	x	88
INPUT 2+	5	-801	-800	88	x	88
INPUT 2-	6	-577	-800	88	x	88
OUTPUT 2	7	-210	-796	88	x	88
OUTPUT 3	8	425	-800	88	x	88
INPUT 3-	9	799	-800	88	x	88
INPUT 3+	10	799	-577	88	x	88
V-	11	801	345	88	x	88
INPUT 4+	12	799	800	88	x	88
INPUT 4-	13	577	800	88	x	88
OUTPUT 4	14	209	796	88	x	88

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